

IN THE CLAIMS:

Please cancel claims 9 and 12.

Please amend claims 2 and 3 as follows:

1 (previously presented): An inspection apparatus for a circuit pattern, comprising:

an irradiating apparatus which is constructed by a plurality of lenses and irradiates light, a laser beam, or a charged particle beam onto a surface of a substrate on which a circuit pattern has been formed;

a detector for detecting a signal which is generated from said substrate;

a memory for temporarily storing the signal detected by said detector and visualized as an image;

a comparing apparatus for comparing said stored signal with a signal obtained by visualizing a corresponding comparison pattern in another region as an image;

a monitor for displaying a defect on said circuit pattern from a result in said comparing apparatus;

an input device for designating a size of a pixel for use in displaying an image of said defect on said monitor in accordance with the width of said circuit pattern; and

a processor responsive to said input device to set the size of a pixel at the detection of said signal in accordance with an input from said input device.

2 (currently amended): An inspection apparatus for a circuit pattern, comprising:

an irradiating apparatus which is constructed by a plurality of lenses and irradiates light, a laser beam, or a charged particle beam onto a surface of a substrate on which a circuit pattern has been formed;

a detector for detecting a signal which is generated from said substrate by said irradiation;

a memory for storing the signal obtained by said detector and visualized as an image, said memory storing an SEM image which is obtained by irradiating said charged particle beam only once to one region on the surface of said substrate;

a comparing apparatus for comparing said signal stored in said memory with a signal obtained by visualizing a corresponding comparison pattern in another region as an image;

a monitor for displaying a defect on said circuit pattern from a result in said comparing apparatus;

a defect classifying apparatus for extracting a feature of the defect on said circuit pattern included in said SEM image and classifying said defect; and

a processor programmed to cause said irradiating apparatus to irradiate said defect on said circuit pattern again, to obtain a finer image, after classifying said defect, and to cause said monitor to selectively display an image of the defect on said circuit pattern obtained from a result in said comparing apparatus or the SEM image obtained by irradiating again said charged particle beam to said defect on the basis of a result of the classification in said defect after classifying in said defect classifying apparatus.

3 (currently amended): An inspection method for a circuit pattern, comprising the steps of:

forming an SEM image by irradiating a charged particle beam only once to one region on a surface of a substrate on which a circuit pattern has been formed;

detecting a signal which is generated from said substrate by said irradiation;

storing a signal obtained by said detection and visualized as an image;

comparing said stored signal with a signal obtained by visualizing a corresponding comparison pattern in another region as an image;

extracting a defect on said circuit pattern from a result of said comparison;

extracting a feature of said defect included in said SEM image;

classifying said defect from said feature;

irradiate said defect on said circuit pattern again after classifying said defect, to obtain a finer image; and

displaying an SEM image of said defect extracted from the result of said comparison after said classifying step formed by said step of irradiating again.

4-9 (cancelled)

10 (previously presented): An inspection method for a circuit pattern, comprising the steps of:

forming an SEM image by irradiating a charged particle beam only once to a surface of a substrate on which a circuit pattern has been formed;

detecting a signal which is generated from said substrate by said irradiation;
storing a signal obtained by said detection and visualized as an image;
comparing said stored signal with a signal obtained by visualizing a corresponding
comparison pattern in another region as an image;
designating a size of a pixel at the detection of said signal for use in displaying an image
of a defect on said monitor in accordance with the width of said circuit pattern; and
displaying a defect on said circuit pattern obtained from a result of said comparison using
said pixel size.

11-12 (Cancelled)